

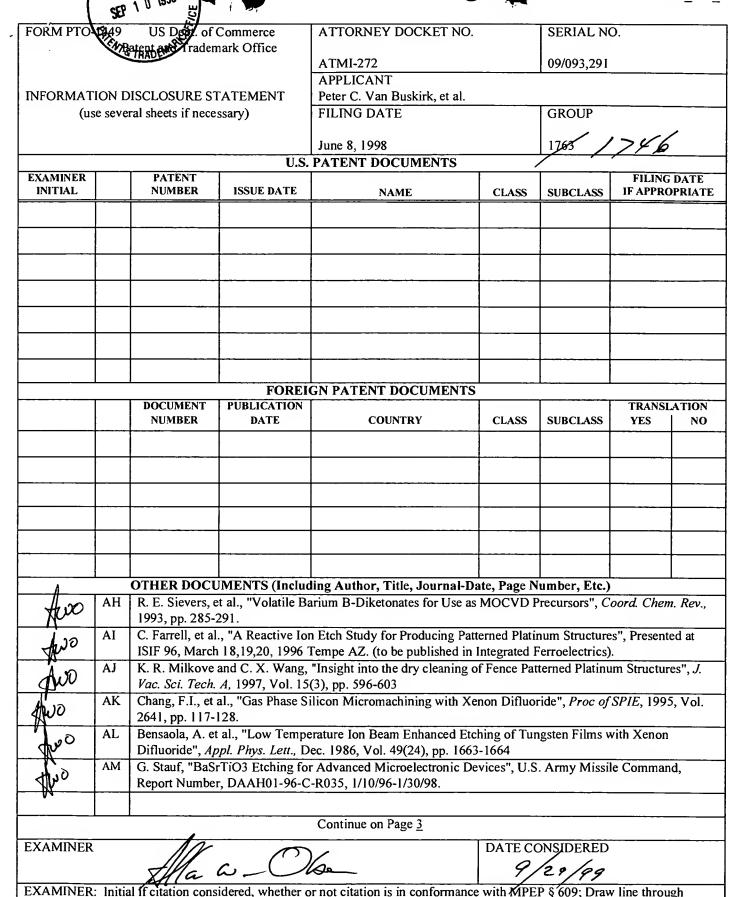
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70	AD	Williams, et al., "Etch Rates for Micromachining Processing", Journ. For Microelectromechanical Systéms,							
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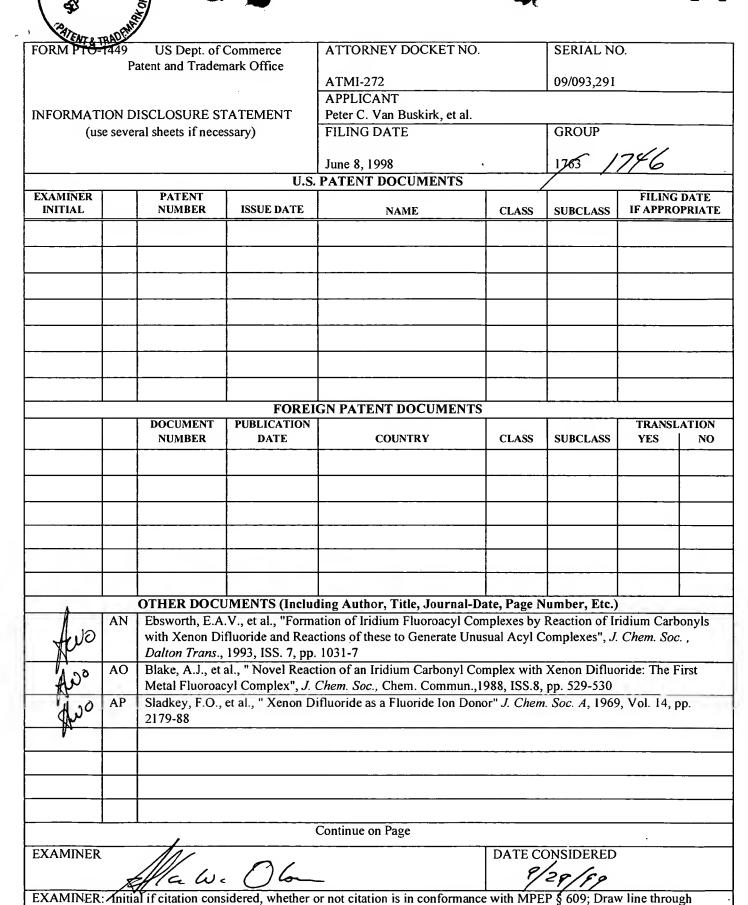
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